USM ICE'26
USM International Conference on Engineering 2026

USM
UNIVERSITI SAINS MALAYSIA

APEX®

USM INTERNATIONAL CONFERENCE ON ENGINEERING 2026

AEROMECH 2026 | AICCE26 | ICRAIEM2026 | RAMM | icenv 2026 | ISIS 2026

ADVANCES AI-DRIVEN AND SUSTAINABILITY-LED GLOBAL IMPACT



28-29 October 2026

Setia SPICE Convention Centre
Penang, **MALAYSIA**

WE LEAD | www.eng.usm.my
Transforming Higher Education for a Sustainable Tomorrow

QS WORLD UNIVERSITY RANKINGS 2027 **#128**

Times Higher Education Sustainability Impact Ratings 2026 **#5** IN THE WORLD | **#1** IN ASIA | **#1** IN THE WORLD SDG 17 Partnerships for the Goals



WELCOME

USM

International Conference on Engineering 2026

USM INTERNATIONAL CONFERENCE ON ENGINEERING 2026

28-29 October 2026

Setia SPICE Convention Centre
Penang, **MALAYSIA**



01	02	03	04	05	06
SCHOOL OF AEROSPACE ENGINEERING	SCHOOL OF CIVIL ENGINEERING	SCHOOL OF MECHANICAL ENGINEERING	SCHOOL OF MATERIALS & MINERAL RESOURCES ENGINEERING	SCHOOL OF CHEMICAL ENGINEERING	**CEDEC** COLLABORATIVE MICROELECTRONIC DESIGN EXCELLENCE CENTRE

THEME

ICE USM Website

"ADVANCES AI-DRIVEN AND SUSTAINABILITY-LED GLOBAL IMPACT"

Table Of **Content**

- USM ICE 2026 at a Glance — Page 4
- Welcome Notes
  - Professor Ir. Dr. Mariatti Jaafar @ Mustapha — Page 5
    Tuanku Syed Sirajuddin Engineering Campus Director
  - Professor Ir. Dr. Fadzli Mohamed Nazri — Page 6
    Chairman ICE 2026
- Opening Remark — Page 7
  Professor Dato' Seri Ir. Dr. Abdul Rahman Mohamed, FASc.
  Vice-Chancellor, Universiti Sains Malaysia
- ICE 2026 Program — Page 8
- FLOOR LAYOUT — Page 9
- AEROMECH 2026 — Page 10
- AICCE 2026 — Page 11
- ICRAIEM 2026 — Page 12
- RAMM 2026 — Page 13
- ICENV 2026 — Page 14
- ISIS 2026 — Page 15
- TALENT DEVELOPMENT BRIEFING PROGRAM — Page 16
- ACKNOWLEDGEMENTS — Page 17
- SPONSORS AND OFFICIAL SUPPORT — Page 18
- CONFERENCE VENUE — Page 19



USM ICE 2026 at a Glance

The USM International Conference on Engineering 2026 (USM ICE 2026) marks a milestone event in conjunction with the 25th anniversary of the Tuanku Syed Sirajuddin Engineering Campus. With the theme **"Advances AI-Driven and Sustainability-Led Global Impact",** the conference highlights cutting-edge research and innovations that address global challenges through engineering excellence. Organized under the umbrella of USM ICE, each School within the Engineering Campus will host its own conference and symposium, creating a dynamic platform for knowledge exchange, collaboration, and showcasing impactful research. This inaugural event reflects Universiti Sains Malaysia's commitment to advancing technology, sustainability and international partnerships.

"ADVANCES AI-DRIVEN AND SUSTAINABILITY-LED GLOBAL IMPACT"

01	02	03	04	05	06
SCHOOL OF AEROSPACE ENGINEERING	SCHOOL OF CIVIL ENGINEERING	SCHOOL OF MECHANICAL ENGINEERING	SCHOOL OF MATERIALS & MINERAL RESOURCES ENGINEERING	SCHOOL OF CHEMICAL ENGINEERING	CEDEC COLLABORATIVE MICROELECTRONIC DESIGN EXCELLENCE CENTRE



Welcome Address

from the Campus Director, Tuanku Syed Sirajuddin Engineering Campus

Assalamualaikum Warahmatullahi Wabarakatuh,

It is my distinct honour and privilege on behalf of the USM Engineering Campus to welcome all delegates to the beautiful state of Penang. You are gathered in a really dynamic region, a nexus of rich cultural heritage and UNESCO-recognized history, and rapid industrial growth. Located conveniently close to important industrial corridors such as Batu Kawan, Penang is known across the world as the “Silicon Valley of the East” and offers an inspiring and highly relevant ecosystem for an engineering conference of this magnitude.

As we convene for this conference, we also take this opportunity to proudly celebrate the 25th anniversary of the USM Engineering Campus. This silver jubilee milestone represents 25 years of commitment to engineering excellence, impactful research, industry collaboration, and human capital development. It is a tribute to the collective efforts of our staff, students, alumni, industry partners and stakeholders who have helped develop the campus into one of the nation’s leading engineering education and research centers. This conference is part of our anniversary celebrations and is an ideal opportunity to reflect on what we have achieved and to chart new pathways for innovation and global collaboration in the years ahead.

Our Engineering Campus, home to a variety of specialized engineering schools and world-renowned Centers of Excellence, has always prided itself on fostering a vibrant and holistic research environment. We bridge the gap between rigorous academic research and the critical needs of industry.

We are always striving to challenge the limits of multi-disciplinary innovation, ensuring our collective research outcomes contribute directly to the Northern Corridor Economic Region (NCER), national development agendas and the acceleration of global technological progress.

The Fourth Industrial Revolution (IR 4.0) and the transition to a circular economy are driving a paradigm shift in the global engineering landscape. We are breaking down traditional academic silos and leveraging synergies across different branches of engineering combining machine learning with mechanical systems, marrying advanced nanomaterials with structural design, and integrating green technologies into everyday industrial processes to redefine how we approach the world’s most complex problems. Academia cannot work in silos anymore; we need to co-create solutions and build future-ready talent with industry leaders and policy makers.

I have no doubt that the state-of-the-art facilities, inter-faculty collaborations and the intellectually stimulating environment on our campus will provide the perfect setting for the discussions you will engage in over the coming days.

I hope you will use this unique multi-conference platform to network across disciplines, question the current quo, share new ideas, and explore future collaborations and research grants.

Also take the time to discover Penang's unique hospitality, rich culture and world-renowned cuisine. I wish you a very productive conference and an inspiring and memorable stay.

YBrs. Professor Ir. Dr. Mariatti Jaafar @ Mustapha
Campus Director, Tuanku Syed Sirajuddin Engineering Campus
Universiti Sains Malaysia



Conference Chair's Foreword

Asalamualaikum Warahmatullahi Wabarakatuh and welcome to the conference,

On behalf of the joint organizing and scientific committees I welcome you to this grand assembly of engineering conferences with a profound sense of pride, gratitude and enthusiasm.

The main objective of this mega event is to provide a dynamic, unifying, and high-level platform for researchers, academicians, industry practitioners and policy makers from various fields to come together. Over the past year, the response to our call for papers has been overwhelming with submissions from around the world. It reflects a profound global desire to share knowledge, benchmark our progress and collaborate across borders. In the face of the challenges of the unprecedented global change, the focus should be on the integrated, adaptive and forward-looking engineering solutions for the test of time.

During the next two days, we will discuss major breakthroughs in all participating engineering tracks. The well-designed program includes keynote addresses by world-class experts, highly specialized parallel technical sessions, booths in industry exhibition and extensive networking opportunities. We are also happy to inform you that the high-quality research presented here will be published in well reputed indexed proceedings and special issues of journals further establishing the academic legacy of this event. We want to show that doing interdisciplinary work is not only good, but essential for our future together. The innovations in these rooms will help lay the foundation for tomorrow's smart cities, advanced manufacturing plants and resilient infrastructures.

An event of this size and complexity is never the work of one person, nor is it the work of a single faculty. My deepest and most sincere gratitude goes to the joint secretariat and the organizing committee. Their tireless dedication, resilience and seamless teamwork over the past several months have brought this ambitious, unified vision to life successfully.

I wish to express my sincere gratitude to our distinguished international advisory board and our rigorous panel of peer-reviewers for maintaining the high scientific standards of this conference. We would like to thank our generous sponsors, government agencies and strategic industry partners, as your continued support across all conference tracks has been key to making this event a resounding success.

Finally, we wish to thank our distinguished keynote speakers, authors and all the participants, particularly the young post-graduate researchers and students who are the future of our profession, for sharing their diverse expertise and lively insights with us in this forum. I urge you strongly to step beyond your specific academic domains, to engage extensively with colleagues from other fields and to forge new collaborative ties.

Thank you for your participation and I wish you an inspiring, thought provoking and very successful conference.

Professor Ir. Dr. Fadzli Mohamed Nazri
Conference Chair
Organizing Committee, International Conference on Engineering 2026



Message

from the Vice-Chancellor, Universiti Sains Malaysia

Assalamualaikum Warahmatullahi Wabarakatuh,

I am delighted to extend a warm welcome to all the distinguished keynote speakers, delegates, industry partners and participants to this premier convergence of international engineering conferences hosted by Universiti Sains Malaysia (USM).

USM is the only university in the country that is an APEX (Accelerated Program for Excellence) university and USM is passionate to lead the sustainability and bring the changes to the world for the benefit of society. Our institutional philosophy stems in the belief that higher education must serve as a catalyst for sustainable development, addressing the urgent needs of today while protecting the future. In a world of rapid technological disruption and environmental issues, the scope of engineering goes far beyond infrastructure and machinery. It is the fundamental engine of all engines for climate resilience, for economic vitality, and for the betterment of humankind.

The global challenges we face cannot be solved in isolation. From climate change and resource scarcity to the complexity of digital transformation, artificial intelligence and rapid urbanization. What they need are integrated, multi-disciplinary solutions that draw on the combined expertise across all engineering sectors, from advanced manufacturing and electrical systems to resilient civil infrastructure, chemical processes, and aerospace technologies. In addition, our engineering efforts should be closely aligned with Environmental, Social, and Governance (ESG) principles and the spirit of the Malaysia MADANI vision, ensuring that technological progress is coupled with human-centric values and the United Nations' Sustainable Development Goals (SDGs).

The joint conference initiative is a strong indication of USM's grand vision of establishing strong global academic partnerships. We bring together the finest brains from diverse engineering disciplines and countries to create a vital, dynamic center for cross-sector working. These are the partnerships that bring together academia, government and industry that can translate the cutting edge theoretical research into real world impacts and commercialized innovations.

I would like to take this opportunity to express my appreciation to all organizing committees of the participating schools for their wonderful synergy in making this grand event possible. To our international guests who have come from afar and to our local participants I wish you a very engaging, productive, and fruitful conference. May the dialogues started here lead to long-term partnerships that will shape the future of engineering worldwide and inspire the next generation of technology leaders.

YBhg. Professor Dato' Seri Ir. Dr. Abdul Rahman Mohamed, FASc.
Vice-Chancellor
Universiti Sains Malaysia

USM INTERNATIONAL CONFERENCE ON ENGINEERING 2026

(USM ICE 2026)

OFFICIATING CEREMONY

Wednesday, 28 October 2026 · 9:00 AM

Setia SPICE Convention Centre, Penang

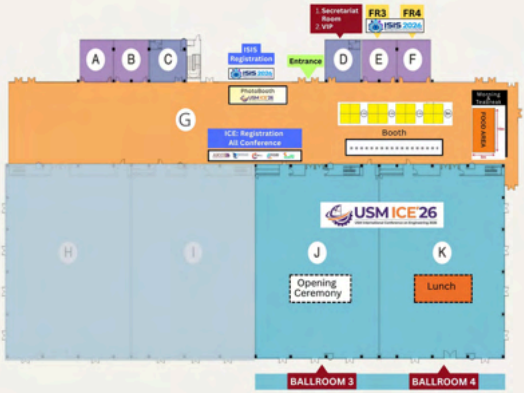
TIME	PROGRAMME
8:15 AM	**Registration**
8:50 AM	**Arrival of the Guest of Honour and VIPs**
9:00 AM	**Negaraku** *Welcoming Remarks and Opening Prayer*
9:10 AM	*Welcome Address:* **Professor Ir. Dr. Mariatti Jaafar@Mustapha** Campus Director Tuanku Syed Sirajuddin Engineering Campus Universiti Sains Malaysia
9:20 AM	*Officiating Speech and Official Launch:* **Professor Dato' Seri Ir. Dr. Abdul Rahman Mohamed, FASc.** Vice-Chancellor Universiti Sains Malaysia
9:30 AM	*Official Launch of:* **USM International Conference on Engineering 2026 (USM ICE 2026)**
9:40 AM	**Refreshments**
10:00 AM	**End of Ceremony**

FLOOR LAYOUT

MEETING & CONFERENCE SPACE

Lower Ground Floor

SETIA SPICE CONVENTION CENTRE

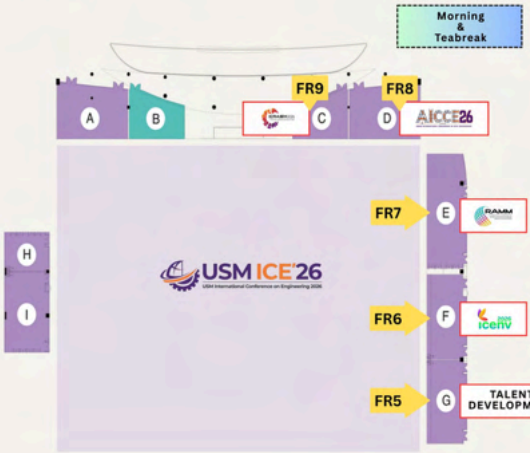


- A Function Room 1
- B Function Room 2
- C VIP Room 1
- D VIP Room 2
- E Function Room 3
- F Function Room 4
- G Grand Foyer
- H Ballroom 1
- I Ballroom 2
- J Ballroom 3
- K Ballroom 4

MEETING & CONFERENCE SPACE

Ground Mezzanine Floor

SETIA SPICE CONVENTION CENTRE



- A Function Room 10
- B Boardroom
- C Function Room 9
- D Function Room 8
- E Function Room 7
- F Function Room 6
- G Function Room 5
- H Function Room 11
- I Function Room 12

AEROMECH 2026

INTERNATIONAL CONFERENCE OF AEROSPACE & MECHANICAL ENGINEERING



CALL FOR PAPER

28-29 OCTOBER 2026

SETIA SPICE CONVENTION CENTRE, PULAU PINANG, MALAYSIA

TOPICS

Aerospace and Mechanical Engineering topics but not limited to:

- Acoustic, Vibration and Noise
- Aerodynamics and Aeroelasticity
- Airworthiness and Regulations
- Avionics and Mission Systems
- Computational Fluid Dynamics
- Design, Testing and Performance
- Energy Harvesting
- Experimental Methods and Measurements
- Fatigue and Reliability
- Finite Element Analysis
- Flight Dynamics and Control
- Flight Testing and Simulation
- Green and Renewable Energy
- Composite, Structures and Materials
- Manufacturing Engineering
- Nanotechnology
- Mechanics and Mechatronics
- Propulsion, Fuel and Combustion
- Robotics and Automation
- Space System and Technology
- Satellite Communication
- Thermodynamics
- Heat and Mass Transfer
- Unmanned Vehicle Design

IMPORTANT DATES

Full Paper Submission	**20 Aug 2026**
Full Paper Notification	**20 Sept 2026**
Early Bird Payment	**30 Sept 2026**
Registration / Payment Deadline	**10 Oct 2026**

FOR MORE INFORMATION

CONTACT:
aeromech@usm.my
04 599 5984

Selected manuscripts will have the opportunity to be published in **Scopus-indexed journal**, subjected to evaluation. Other manuscripts will be published in indexed Proceeding.

USM UNIVERSITI SAINS MALAYSIA | APEX | USM ICE'26 USM International Conference on Engineering 2026

AICCE26 AWAM INTERNATIONAL CONFERENCE IN CIVIL ENGINEERING

THEME

Civil Engineering Excellence for a Resilient and Sustainable Tomorrow



AWAM INTERNATIONAL CONFERENCE IN CIVIL ENGINEERING 2026

in conjunction with

MALAYSIAN UNIVERSITIES TRANSPORT RESEARCH FORUM CONFERENCE

28 29 October 2026

SETIA SPICE CONVENTION CENTER
PENANG, MALAYSIA

JOIN NOW

IMPORTANT DATES

Full Paper Deadline	30 June 2026
Acceptance Notification	31 July 2026
Early Bird Registration	31 August 2026
Registration / Payment Deadline	30 September 2026

REGISTRATION & PARTICIPATION FEES

PARTICIPANT CATEGORY	EARLY REGISTRATION	NORMAL REGISTRATION
Local Participant	RM 1,500.00	RM 1,800.00
USM Participant*	RM 1,300.00	RM 1,500.00
International Participant*	USD 500.00	USD 600.00
Attendance (Non-Presenter)	Normal Registration: RM 800.00 USD 300 .00	

NOTES:
1. * Verification via student matrix/ ID card.
2. Participants may present more than one paper upon payment of a additional fee.

OVERVIEW

The AWAM International Conference on Civil Engineering 2026 (AICCE'26) provides an international platform for researchers, academicians, engineers, industry practitioners, policymakers, and students to share knowledge, research findings, and practical innovations in civil engineering.

In line with the conference theme, AICCE'26 highlights the role of civil engineering in shaping a future that is resilient, inclusive, innovative, and environmentally responsible. The conference welcomes contributions that address both fundamental and applied issues in civil engineering, with emphasis on solutions that support sustainable infrastructure, climate resilience, efficient resource use, digital transformation, and societal well-being.

As hosted under the spirit of Universiti Sains Malaysia and the School of Civil Engineering (SoCE), the conference reflects a commitment to academic excellence, impactful research, industry relevance, and sustainability-driven engineering practice.

Call For Registration
https://aicce.eng.usm.my/

CALL FOR PAPER

Organized By:

USM UNIVERSITI SAINS MALAYSIA | APEX | TSAM

Co- Organized By:

REDAC

Contact us :
SoCE@USM SCHOOL OF CIVIL ENGINEERING
Email: aicce@usm.my
Phone: +604-

LEAFLORE

School Of Mechanical Engineering

Co-organizers



The 2nd International Conference on Recent Advances on Industrial Engineering and Manufacturing 2026

For more details, please visit
https://icraiem.eng.usm.my/

Important Datelines:

- **Before 1st-5th October 2026**
  Registration & full paper submission
- **Before 15th July 2026**
  ~~Early bird registration and payment~~
- **2 weeks after full paper submission**
  Notification of acceptance
- **Before 15th October 2026**
  Revised full paper submission and full payment

*Accepted papers will be published as a book chapter in Springer Book Series - Advanced Structured Materials (SCOPUS indexed)

Conference fee:

International Participant
Presenter :USD 600
Early bird :USD 500
Audience :USD 300

Local Participant
Presenter: RM 1800
Early bird : RM 1500

USM Participant
Presenter: RM 1500
Early Bird : RM 1300
Local Audience: RM 800

SCAN FOR REGISTRATION & PAPER SUBMISSION

*Group registration (more than 3) will get 10% discount

28th -29th October 2026

Setia Spice Convention Center, Penang, Malaysia

Call for papers!

Are you interested to be an invited speaker?
Submit your CV to mebaha@usm.my

Theme

Smart Manufacturing:
AI and Sustainability in Engineering Innovation.

Topics of Interest

- AI & Smart Manufacturing
- Manufacturing Processes & Automation
- Precision Engineering & Metrology
- Advanced Materials & Micro/Nano Manufacturing
- Modeling, Simulation & Digital Engineering
- Sustainable Manufacturing & Industrial Systems
- Intelligent Maintenance & Asset Management
- Human-Centered Manufacturing & Safety

Keynote Speaker

Dr. Paul Wood



Professor of Advanced Manufacturing and Director of the Institute of Innovation in Sustainable Engineering, University Of Derby

Dr. Boey Kok Hong



MD and Founder, Solid Precision Engineering Sdn. Bhd.

Mr. Lim Yew Kee



IET, United Kingdom

USM ICE'26
USM International Conference on Engineering 2026

SCAN HERE

RAMM 2026

9TH INTERNATIONAL CONFERENCE ON RECENT ADVANCES IN MATERIALS, MINERALS & ENVIRONMENT

PUBLICATION OPPORTUNITY:
Springer Book Chapters for Accepted Papers

REGISTER NOW

https://ramm.eng.usm.my

28 - 30 Oct, 2026

Setia SPICE Convention Centre
Penang, Malaysia

'AI DRIVEN NEXT GENERATION MATERIALS AND SUSTAINABLE RESOURCE ENGINEERING FOR A RESILIENT FUTURE'

CALL FOR PAPERS

Topics :

1. Next Generation Materials for a Sustainable Future
2. Recent Innovations in Sustainable Polymeric Materials and Applications
3. Advances in Mineral Resources Engineering and AI for Sustainable Resource Management

Important Deadlines

- **Abstract Submission**
  06 October 2026
- **Abstract Notification**
  06 October 2026
- **Full Paper Submission**
  28 October 2026
- **Early Bird Payment**
  31 August 2026
- **Payment Deadline**
  15 September 2026

The Secretariat RAMM 2026
School of Materials and Mineral Resources Engineering
Tuanku Syed Sirajuddin Engineering Campus,
Universiti Sains Malaysia
14300 Nibong Tebal, Penang. MALAYSIA.

Assoc. Prof. Dr. Tuti Katrina Abdullah
tutikatrina@usm.my

Pn. Suhani Abdullah
srsuhani@usm.my

https://wa.me/6045996101

ramm@usm.my +604-5996101

REGISTRATION & PARTICIPANT FEES

LOCAL PARTICIPANTS:	
Early Bird	RM 1500
Regular	RM 1800
Attendance (Non-Presenter)	RM 800

USM PARTICIPANT:	
Early Bird	RM 1300
Regular	RM 1500

INTERNATIONAL PARTICIPANTS:	
Early Bird	USD 500
Regular	USD 600
Attendance (Non-Presenter)	USD 300

USM UNIVERSITI SAINS MALAYSIA | APEX | 25 | USM ICE'26 | icenv 2026

9th INTERNATIONAL CONFERENCE ON ENVIRONMENT 2026

ICENV 2026

28-29 OCTOBER 2026 | **09:00 AM - 05:00 PM (GMT+8)** | **SETIA SPICE CONVENTION CENTRE, PENANG, MALAYSIA**

THEME

Advancing Smart and Sustainable Engineering Technologies toward a Low-Carbon Future

SCOPE OF TOPICS

- Sustainable Process Engineering
- Biotechnology and Environmental Solutions
- Environmental Monitoring and Analysis
- Waste Management and Valorisation
- Clean Energy and Resource Utilization
- Sustainable Materials and Design
- Water and Air Quality Management
- Ecosystem Conservation and Restoration
- Process Safety and Environmental Health
- Education and Outreach for Sustainability

POTENTIAL PUBLICATION

Selected papers will be published in IOP Conference Series (*Scopus-indexed*) or *invited for submission to the Journal of Physical Science*, subject to rigorous peer review and editorial approval.

PLENARY SPEAKERS



Prof. Dr. Yoshinori Takashima

"Dynamic Polymer Networks with Enzymatic Degradation and Self-Healing Functions"

The University of Osaka
JAPAN



Prof. Dr. Chi-Wei Lan

"CO_2-Based Ionic Liquids as Green Solvents for Microalgal Lipid Extraction: Synthesis, Application, and Recyclability"

Yuan Ze University
TAIWAN



Prof. Dr. Guowu Zhan

"Design of Bifunctional Catalysts using Biomass Templates for CO_2 Thermal Hydrogenation"

Huaqiao University
CHINA



Ir. Ts. Dr. Farahdila Binti Kadirkhan

Carbon Capture Utilisation & Storage (CCUS) Technology for low carbon solution

Petroleum Nasional Berhad (PETRONAS)
MALAYSIA

IMPORTANT DATES

Early Bird Registration Deadline	Abstract Submission Deadline (EXTENDED)	Notification of Acceptance	Full Paper Submission Deadline
AUGUST 15, 2026	OCTOBER 15, 2026	OCTOBER 20, 2026	OCTOBER 30, 2026

CONFERENCE DATES | OCTOBER 28–29, 2026

REGISTER NOW!!!

Scan The QR code to register

CONTACT THE SECRETARIAT OF ICENV 2026

icenv@usm.my | +604 59[illegible]

School of Chemical Engineering,
Tuanku Syed Sirajuddin Engineering Campus,
Universiti Sains Malaysia, 14300, Nibong Tebal,
Pulau Pinang, Malaysia.

https://icenv.eng.usm.my/2026/index.php

ISIS 2026
INTERNATIONAL SEMICONDUCTOR INNOVATION SYMPOSIUM

INTERNATIONAL SEMICONDUCTOR INNOVATION SYMPOSIUM (ISIS 2026)

Connecting Innovation, Talent & the Future of Semiconductors

The International Semiconductor Innovation Symposium 2026 (ISIS 2026) is a strategic platform bringing together industry leaders, academics, researchers, students, government agencies and technology stakeholders to explore the latest innovations and emerging trends shaping the global semiconductor industry.

Through keynote sessions, industry forums and focused technical sessions, ISIS 2026 aims to strengthen collaboration, accelerate knowledge exchange and support the development of a resilient and competitive semiconductor ecosystem.



Register Now!

PROGRAMME HIGHLIGHTS

KEYNOTE 1
GaN Technology Demand: Rising with AI Server Chip Growth

KEYNOTE 2
Beyond the Silicon: Scaling AI Infrastructure and the Semiconductor Talent Pipeline

PARALLEL TRAINING SESSION 1
AI-Assisted CMOS RF Power Amplifier Design and Optimization Using Cadence Virtuoso

PARALLEL TRAINING SESSION 2
Interposer Technology for Advanced Packaging Applications

FORUM 1
AI Semiconductor & Future Chip Design Ecosystem

WHO SHOULD ATTEND?

- Industry Professionals
- Academics & University Researchers
- Students
- Government Agencies
- Semiconductor & Technology Stakeholders

REGISTRATION
FREE ADMISSION
Seats are **LIMITED!**
Meals & Refreshments Included

Organized by:
USM, APEX, USM ICE'26 (USM International Conference on Engineering 2026), CEDEC

Co-organized by:
TMSTIC, ICDEC

Supported by:
MINISTRY OF HIGHER EDUCATION AI Enhancement Semiconductor Init..., ICE

SETIA SPICE CONVENTION CENTER
PENANG, MALAYSIA

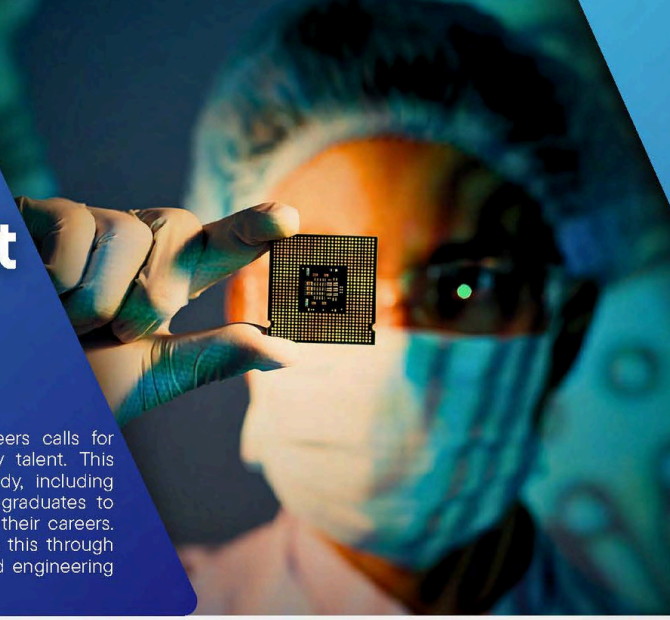
28th OCTOBER 2026
8.30AM – 5.00PM

for any inquiries:
sofiyah@usm.my, nuha@usm.my
tel: 04-6535622

USM
UNIVERSITI SAINS MALAYSIA

APEX

Talent Development Briefing Program



The growing demand for skilled E&E engineers calls for stronger pathways to develop industry-ready talent. This briefing introduces pathways to Master's study, including APEL.A, enabling industry professionals and graduates to further their technical expertise and advance their careers. The Talent Development Programme supports this through postgraduate education, talent recruitment and engineering technology training.

APEL.A @ USM

A flexible pathway that recognises work experience, practical skills and prior learning for access to higher education.

For working professionals, industry practitioners and experienced individuals seeking to further their academic journey.

apel.usm.my

NEW MSc PROGRAMME

A specialised postgraduate programme focusing on **Advanced Semiconductor Packaging**, designed to develop industry-ready expertise in emerging packaging technologies.

A multidisciplinary involving **5 Schools/Centres at USM**: School of Materials and Mineral Resources Engineering • School of Electric and Electronic Engineering • School of Mechanical Engineering • Institute of Nano Optoelectronics Research and Technology (INOR) • Collaborative Microelectronic Design Excellence Centre (CEDEC)

Core Courses

Advanced Material Characterisation for Semiconductor Packaging | Product Failure Analysis & Computational Aided Engineering | Science and Engineering Research Methodology | Advanced Chip-package-board Co-design | Research Project

admission.usm.my

COME & MEET US!

USM ICE'26
USM International Conference on Engineering 2026

28 October 2026 | 2.30 pm - 5.00 pm
Setia SPICE Convention Center, Penang

ENGINEERING POSTGRADUATE PROGRAMMES

Offers Master of Science (MSc) programmes through Research Mode and Mixed Mode, providing opportunities for graduates and professionals to deepen their expertise in engineering and related fields.

MSc by Mixed Mode

Electronic System Design Engineering | Microelectronic Engineering | Fire Safety Engineering | Materials Engineering | Advanced Manufacturing Engineering with Management | Advanced Semiconductor Packaging | Data Driven Sustainable Engineering

MSc & PhD by Research

Aerospace Engineering | Civil Engineering | Chemical Engineering | Materials Engineering | Mineral Resources Engineering | Polymer Engineering | Electrical & Electronic Engineering | Microelectronic Systems Engineering | River and Urban Drainage Engineering | Mechanical Engineering | Manufacturing Engineering

ELECTRONIC ENGINEERING – NOW ENROLLING

The School of Electrical & Electronic Engineering, USM is now offering a new intake for **Electronic Engineering at the Main Campus.**

First Intake: Academic Session 2026/2027

SESSION WITH HRD CORP

HRD CORP
HUMAN RESOURCE DEVELOPMENT CORPORATION

Exploring opportunities for stronger industry-institution collaboration through HRD Corp, with a focus on professional training, skills development and continuous learning to equip academic staff and engineering talent with capabilities aligned with industry needs.

WHO SHOULD ATTEND

- Industries related to electronic and semiconductor

Further Information:

WE LEAD | www.eng.usm.my
Transforming Higher Education for a Sustainable Tomorrow

#5 IN THE WORLD | #1 IN ASIA | #1 IN THE WORLD SDG17



ACKNOWLEDGEMENTS

The organizing committee is very grateful for the support and generosity of the following contributions towards the success of the USM ICE2026

- Director's Office, Tuanku Syed Sirajuddin Engineering Campus
- School of Aerospace Engineering
- School of Civil Engineering
- School of Mechinical Engineering
- School of Material dan Mineral Resource Engineering
- School of Chemical Engineering
- Collaborative Microelectronic Design Excellence Centre (CEDEC)
- Education Malaysia Global Services
- Ministry of Higher Education, Department of Higher Education, AI Enhancement Semiconductor Initiative

The organizing committee also wishes to extend its gratitude to individuals who had given support and assistance towards the success of USM ICE2026.

SPONSORS AND OFFICIAL SUPPORT

Education MALAYSIA GLOBAL SERVICES

MINISTRY OF HIGHER EDUCATION
DEPARTMENT OF HIGHER EDUCATION
AI Enhancement Semiconductor Initiative



CONFERENCE VENUE

SETIA SPICE CONVENTION CENTRE

Penang, Malaysia



A modern and sustainable venue for international collaboration, knowledge exchange and innovation, welcoming delegates to connect and shape the future together.



MY NOTES



USM LEAD

USM ICE'26

USM International Conference on Engineering 2026

Organized by



ICE USM Website

Supported by

MINISTRY OF HIGHER EDUCATION
DEPARTMENT OF HIGHER EDUCATION
AI Enhancement Semiconductor Initiative